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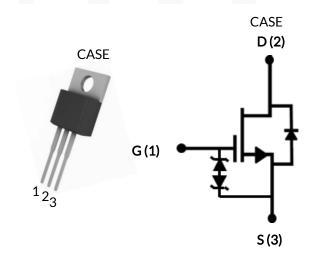






DATASHEET

UJ3C065030T3S



Part Number	Package	Marking
UJ3C065030T3S	TO-220-3L	UJ3C065030T3S



Silicon Carbide (SiC) Cascode JFET -EliteSiC, Power N-Channel, TO-220-3L, 650 V, 27 mohm

Rev. E, January 2025

Description

This SiC FET device is based on a unique 'cascode' circuit configuration, in which a normally-on SiC JFET is co-packaged with a Si MOSFET to produce a normally-off SiC FET device. The device's standard gate-drive characteristics allows for a true "drop-in replacement" to Si IGBTs, Si FETs, SiC MOSFETs or Si superjunction devices. Available in the TO-220-3L package, this device exhibits ultralow gate charge and exceptional reverse recovery characteristics, making it ideal for switching inductive loads and any application requiring standard gate drive.

Features

- Typical on-resistance $R_{DS(on),typ}$ of $27m\Omega$
- Maximum operating temperature of 175° C
- Excellent reverse recovery
- Low gate charge
- Low intrinsic capacitance
- ESD protected, HBM class 2
- AECQ Qualified

Typical applications

- EV charging
- PV inverters
- Switch mode power supplies
- Power factor correction modules
- Motor drives
- Induction heating





Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
Drain-source voltage	V _{DS}		650	V
Gate-source voltage	V _{GS}	DC	-25 to +25	V
Continuous drain current ¹	1	T _C = 25°C	85	А
Continuous drain current	ID	T _C = 100°C	62	А
Pulsed drain current ²	I _{DM}	T _C = 25°C	230	А
Single pulsed avalanche energy ³	E _{AS}	L=15mH, I _{AS} =4A	120	mJ
Power dissipation	P _{tot}	T _C = 25°C	441	W
Maximum junction temperature	T _{J,max}		175	°C
Operating and storage temperature	T _J , T _{STG}		-55 to 175	°C
Max. lead temperature for soldering, 1/8" from case for 5 seconds	TL		250	°C

1. Limited by $T_{J,max}$

2. Pulse width t_p limited by $T_{J,max}$

3. Starting $T_J = 25^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Test Conditions	Value			Units
Parameter			Min	Тур	Max	Units
Thermal resistance, junction-to-case	$R_{\theta JC}$			0.26	0.34	°C/W









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Electrical Characteristics (T_J = +25°C unless otherwise specified)

Typical Performance - Static

Parameter	Symbol	Test Conditions	Value			L lasta
			Min	Тур	Max	Units
Drain-source breakdown voltage	BV _{DS}	V _{GS} =0V, I _D =1mA	650			V
Total drain leakage current		V _{DS} =650V, V _{GS} =0V, T _J =25°C		6	150	- μΑ
	I _{DSS}	V _{DS} =650V, V _{GS} =0V, T _J =175°C		30		
Total gate leakage current	I _{GSS}	V _{DS} =0V, T _J =25°C, V _{GS} =-20V / +20V		6	±20	μΑ
Drain-source on-resistance	R _{DS(on)}	V _{GS} =12V, I _D =50A, T _J =25°C		27	35	
		V _{GS} =12V, I _D =50A, T _J =125°C		35		mΩ
		V _{GS} =12V, I _D =50A, T _J =175°C		43		
Gate threshold voltage	V _{G(th)}	V_{DS} =5V, I_{D} =10mA	4	5	6	V
Gate resistance	R _G	f=1MHz, open drain		4.5		Ω

Typical Performance - Reverse Diode

Parameter	Symbol	Test Conditions	Value			Units
Faranieter			Min	Тур	Max	Units
Diode continuous forward current ¹	I _S	T _C =25°C			85	А
Diode pulse current ²	$I_{S,pulse}$	T _C =25°C			230	А
Forward voltage	V _{FSD}	V _{GS} =0V, I _F =20A, T _J =25°C		1.3	1.4	V
		V _{GS} =0V, I _F =20A, T _J =175°C		1.35		
Reverse recovery charge	Q _{rr}	V_{R} =400V, I _F =50A, V_{GS} =0V, R _{G_EXT} =20Ω		400		nC
Reverse recovery time	t _{rr}	di/dt=1550A/µs, Tj=150°C		33		ns





Typical Performance - Dynamic

Parameter	Symbol	Test Conditions	Value			L la the
			Min	Тур	Max	- Units
Input capacitance	C _{iss}	- V _{DS} =100V, V _{GS} =0V -		1500		pF
Output capacitance	C _{oss}	f=100kHz		320		
Reverse transfer capacitance	C _{rss}	1-100KHZ		2.3		
Effective output capacitance, energy related	C _{oss(er)}	$V_{DS}=0V$ to 400V, $V_{GS}=0V$		230		pF
Effective output capacitance, time related	C _{oss(tr)}	V _{DS} =0V to 400V, V _{GS} =0V		520		pF
C _{OSS} stored energy	E _{oss}	V _{DS} =400V, V _{GS} =0V		18.5		μJ
Total gate charge	Q _G	- V _{DS} =400V, I _D =50A, $-$ V _{GS} = -5V to15V $-$		51		nC
Gate-drain charge	Q_{GD}			11		
Gate-source charge	Q_{GS}	V _{GS} - 5V (015V		19		
Turn-on delay time	t _{d(on)}			36		
Rise time	t _r	V _{DS} =400V, I _D =50A, Gate		22		
Turn-off delay time	$t_{d(off)}$	Driver =-5V to +15V,		56		ns
Fall time	t _f	Turn-on $R_{G,EXT}=1\Omega$, Turn-off $R_{G,EXT}=20\Omega$		15		
Turn-on energy	E _{ON}	Inductive Load,		472		
Turn-off energy	E _{OFF}	FWD: UJ3D065030TS,		257		μ
Total switching energy	E _{TOTAL}	T_=150°C		729		





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Typical Performance Diagrams

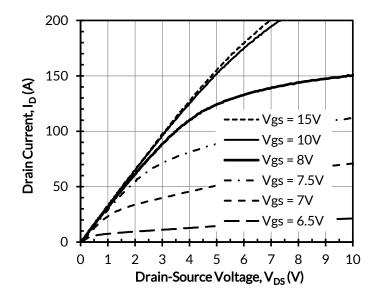


Figure 1. Typical output characteristics at $T_J = -55^{\circ}C$, tp < 250µs

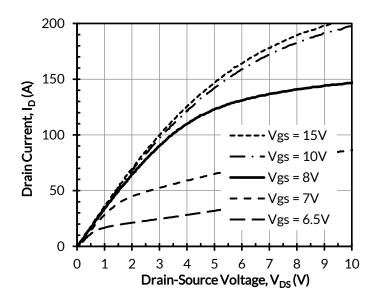


Figure 2. Typical output characteristics at $T_J = 25^{\circ}C$, tp < 250µs

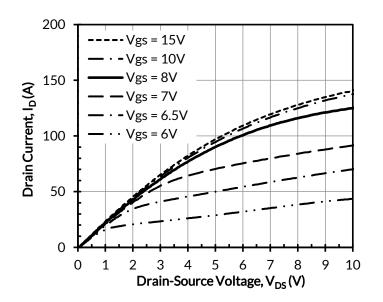


Figure 3. Typical output characteristics at $T_J = 175^{\circ}C$, tp < 250µs

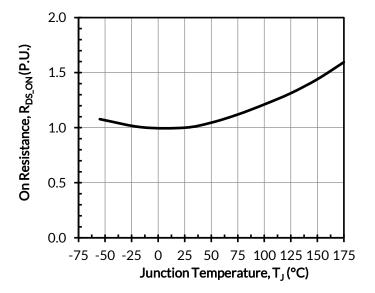


Figure 4. Normalized on-resistance vs. temperature at V_{GS} = 12V and I_D = 50A





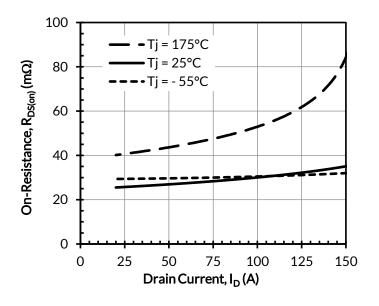


Figure 5. Typical drain-source on-resistances at V_{GS} = 12V

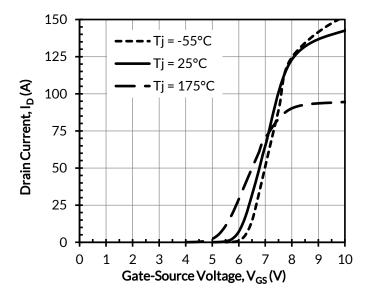


Figure 6. Typical transfer characteristics at V_{DS} = 5V

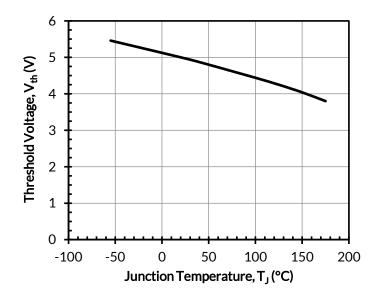


Figure 7. Threshold voltage vs. junction temperature at V_{DS} = 5V and I_{D} = 10mA

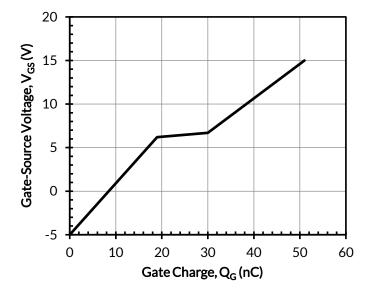


Figure 8. Typical gate charge at V_{DS} = 400V and I_{D} = 50A





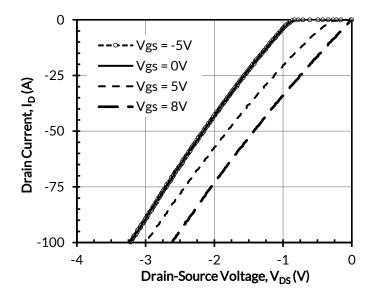


Figure 9. 3rd quadrant characteristics at $T_J = -55^{\circ}C$

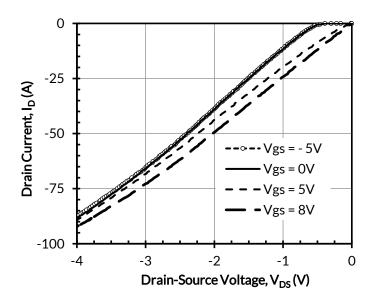


Figure 11. 3rd quadrant characteristics at $T_J = 175^{\circ}C$

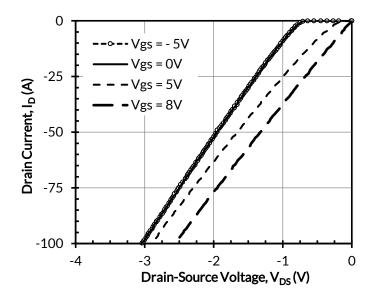


Figure 10. 3rd quadrant characteristics at $T_J = 25^{\circ}C$

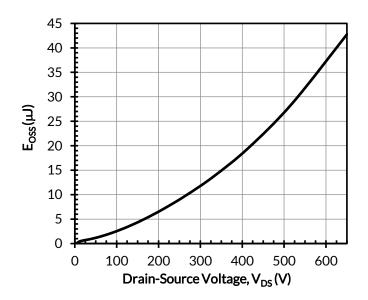


Figure 12. Typical stored energy in C_{OSS} at V_{GS} = 0V



10,000

1,000

100

10

1

0

Capacitance, C (pF)

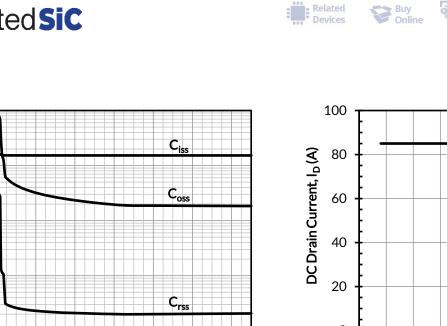


Figure 13. Typical capacitances at f = 100kHz and V_{GS} = 0V

300

Drain-Source Voltage, V_{DS} (V)

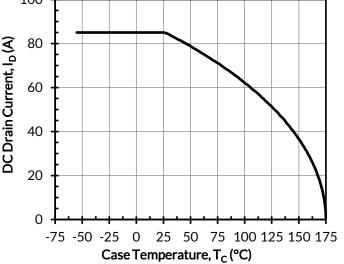
400

500

600

200

100



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Figure 14. DC drain current derating

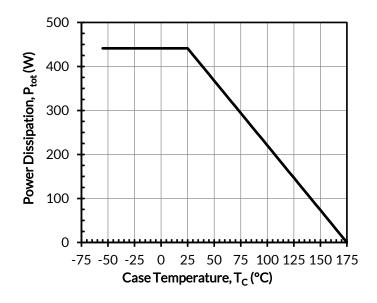


Figure 15. Total power dissipation

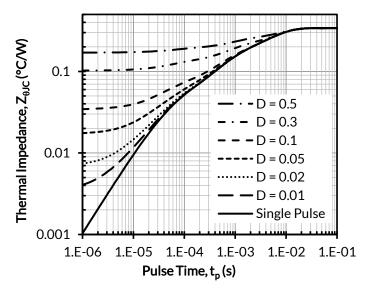


Figure 16. Maximum transient thermal impedance



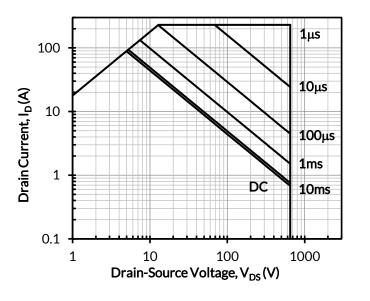
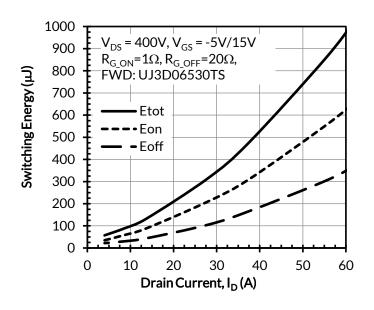


Figure 17. Safe operation area at T_{C} = 25°C, D = 0, Parameter $t_{\rm p}$



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Figure 18. Clamped inductive switching energy vs. drain current at $T_J = 150^{\circ}C$

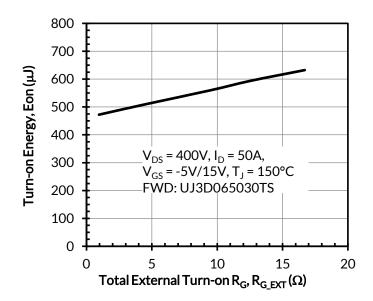


Figure 19. Clamped inductive switching turn-on energy vs. R_{G,EXT_ON}

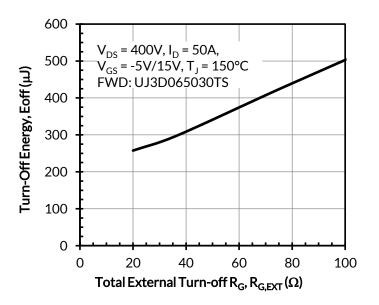


Figure 20. Clamped inductive switching turn-off energy vs. $R_{G,EXT OFF}$





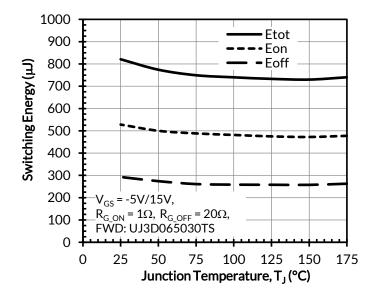


Figure 21. Clamped inductive switching energy vs. junction temperature at V_{DS} =400V and I_D = 50A

Applications Information

SiC FETs are enhancement-mode power switches formed by a highvoltage SiC depletion-mode JFET and a low-voltage silicon MOSFET connected in series. The silicon MOSFET serves as the control unit while the SiC JFET provides high voltage blocking in the off state. This combination of devices in a single package provides compatibility with standard gate drivers and offers superior performance in terms of low on-resistance ($R_{DS(on)}$), output capacitance (C_{oss}), gate charge (Q_G), and reverse recovery charge (Qrr) leading to low conduction and switching losses. The SiC FETs also provide excellent reverse conduction capability eliminating the need for an external anti-parallel diode.

Like other high performance power switches, proper PCB layout design to minimize circuit parasitics is strongly recommended due to the high dv/dt and di/dt rates. An external gate resistor is recommended when the FET is working in the diode mode in order to achieve the optimum reverse recovery performance. For more information on SiC FET operation, see www.unitedsic.com.

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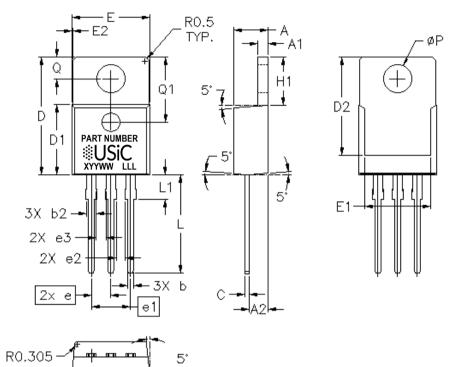
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TO-220-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

PACKAGE OUTLINE



DIM	INC	ES MILLIM		IETERS	
	MIN	MAX	MIN	MAX	
Α	0.140	0.190	3.56	4.83	
A1	0.020	0.055	0.51	1.40	
A2	0.080	0.115	2.03	2.92	
b	0.015	0.040	0.38	1.02	
b2	0.045	0.070	1.14	1.78	
С	0.014	0.024	0.36	0.61	
D	0.560	0.650	14.22	16.51	
D1	0.330	0.355	8.38	9.02	
D2	0.480	0.507	12.19	12.88	
E	0.380	0.420	9.65	10.67	
е	0.100 BSC	<u>.</u>	2.54 BSC		
e1	0.200 BSC		5.08 BSC		
E1	0.270	0.350	6.86	8.89	
E2	-	0.030	-	0.76	
L	0.500	0.580	12.70	14.73	
L1	-	0.250	-	6.35	
ØР	0.139	0.161	3.53	4.09	
Н	0.230	0.270	5.84	6.86	
Q	0.100	0.135	2.54	3.43	
Q1	0.330	0.340	8.38	8.64	



PART MARKING

PART NUMBER SUSSE XYYWW LLL

PART NUMBER = REFER TO DS_PN DECODER FOR DETAILS

X = ASSEMBLY SITE YY = YEAR WW = WORK WEEK LLL = LOT ID

PACKING TYPE

ANTI-STATIC TUBE

QUANTITY / TUBE : 50 UNITS

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